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Renesas Technology Corp.
Customer Support Dept.
April 1, 2003

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HD74LV86A

Quad. 2-input Exclusive-OR Gates



ADE-205-257B (Z)

3rd. Edition
Aug. 2001

Description

The HD74LV86A performs the Boolean functions $Y = A \oplus B$ or $Y = \overline{A}B + A\overline{B}$ in positive logic. A common application is as a true/complement element. If one of the inputs is low, the other input will be reproduced in true form at the output. If one of the inputs is high, the other input will be reproduced inverted form at the output. Low-voltage and high-speed operation is suitable for the battery-powered products (e.g., notebook computers), and the low-power consumption extends the battery life.

Features

- $V_{CC} = 2.0 \text{ V}$ to 5.5 V operation
- All inputs $V_{IH} (\text{Max.}) = 5.5 \text{ V}$ ($@V_{CC} = 0 \text{ V}$ to 5.5 V)
- All outputs $V_O (\text{Max.}) = 5.5 \text{ V}$ ($@V_{CC} = 0 \text{ V}$)
- Typical V_{OL} ground bounce $< 0.8 \text{ V}$ ($@V_{CC} = 3.3 \text{ V}$, $T_a = 25^\circ\text{C}$)
- Typical V_{OH} undershoot $> 2.3 \text{ V}$ ($@V_{CC} = 3.3 \text{ V}$, $T_a = 25^\circ\text{C}$)
- Output current $\pm 6 \text{ mA}$ ($@V_{CC} = 3.0 \text{ V}$ to 3.6 V), $\pm 12 \text{ mA}$ ($@V_{CC} = 4.5 \text{ V}$ to 5.5 V)

Function Table

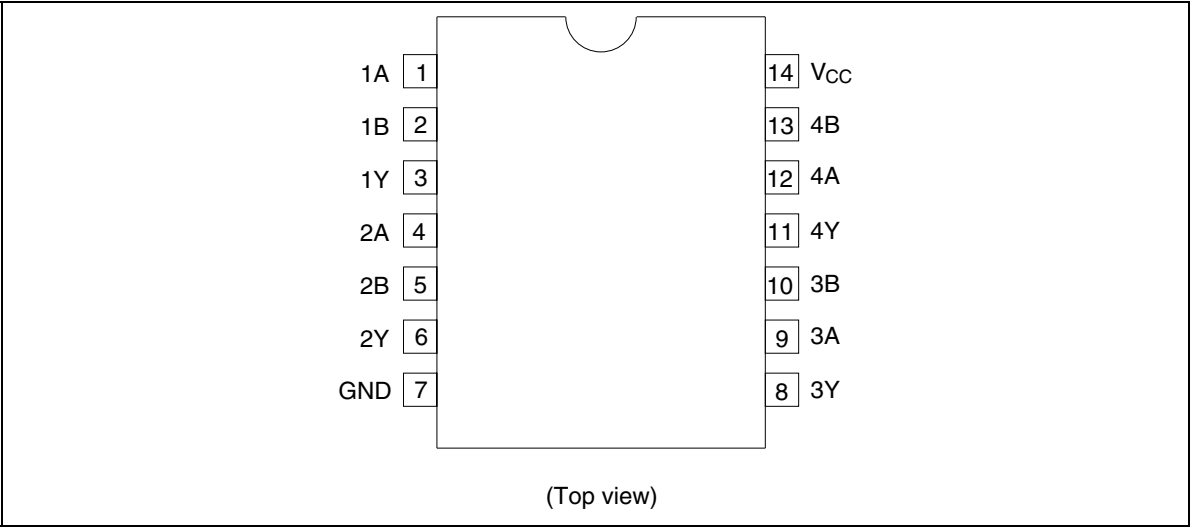
Inputs

A	B	Output Y
L	L	L
L	H	H
H	L	H
H	H	L

Note: H: High level

L: Low level

Pin Arrangement



Absolute Maximum Ratings

Item	Symbol	Ratings	Unit	Conditions
Supply voltage range	V_{CC}	−0.5 to 7.0	V	
Input voltage range* ¹	V_I	−0.5 to 7.0	V	
Output voltage range* ^{1, 2}	V_O	−0.5 to $V_{CC} + 0.5$	V	Output: H or L
		−0.5 to 7.0		V_{CC} : OFF
Input clamp current	I_{IK}	−20	mA	$V_I < 0$
Output clamp current	I_{OK}	±50	mA	$V_O < 0$ or $V_O > V_{CC}$
Continuous output current	I_O	±25	mA	$V_O = 0$ to V_{CC}
Continuous current through V_{CC} or GND	I_{CC} or I_{GND}	±50	mA	
Maximum power dissipation at $T_a = 25^\circ\text{C}$ (in still air)* ³	P_T	785	mW	SOP
		500		TSSOP
Storage temperature	T_{stg}	−65 to 150	°C	

Notes: The absolute maximum ratings are values which must not individually be exceeded, and furthermore, no two of which may be realized at the same time.

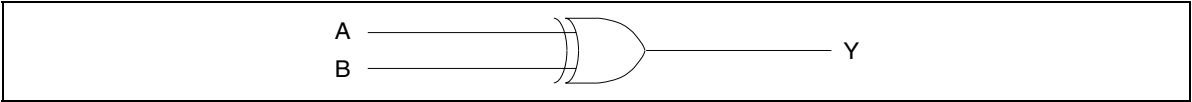
1. The input and output voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. This value is limited to 5.5 V maximum.
3. The maximum package power dissipation was calculated using a junction temperature of 150°C.

Recommended Operating Conditions

Item	Symbol	Min	Max	Unit	Conditions
Supply voltage range	V_{CC}	2.0	5.5	V	
Input voltage range	V_I	0	5.5	V	
Output voltage range	V_O	0	V_{CC}	V	
Output current	I_{OH}	—	−50	μA	$V_{CC} = 2.0\text{ V}$
		—	−2	mA	$V_{CC} = 2.3\text{ to }2.7\text{ V}$
		—	−6		$V_{CC} = 3.0\text{ to }3.6\text{ V}$
		—	−12		$V_{CC} = 4.5\text{ to }5.5\text{ V}$
	I_{OL}	—	50	μA	$V_{CC} = 2.0\text{ V}$
		—	2	mA	$V_{CC} = 2.3\text{ to }2.7\text{ V}$
		—	6		$V_{CC} = 3.0\text{ to }3.6\text{ V}$
		—	12		$V_{CC} = 4.5\text{ to }5.5\text{ V}$
Input transition rise or fall rate	$\Delta t / \Delta v$	0	200	ns/V	$V_{CC} = 2.3\text{ to }2.7\text{ V}$
		0	100		$V_{CC} = 3.0\text{ to }3.6\text{ V}$
		0	20		$V_{CC} = 4.5\text{ to }5.5\text{ V}$
Operating free-air temperature	T_a	−40	85	°C	

Note: Unused or floating inputs must be held high or low.

Logic Diagram



DC Electrical Characteristics

Ta = -40 to 85°C

Item	Symbol	V _{CC} (V)*	Min	Typ	Max	Unit	Test Conditions
Input voltage	V _{IH}	2.0	1.5	—	—	V	
		2.3 to 2.7	V _{CC} × 0.7	—	—		
		3.0 to 3.6	V _{CC} × 0.7	—	—		
		4.5 to 5.5	V _{CC} × 0.7	—	—		
	V _{IL}	2.0	—	—	0.5		
		2.3 to 2.7	—	—	V _{CC} × 0.3		
		3.0 to 3.6	—	—	V _{CC} × 0.3		
		4.5 to 5.5	—	—	V _{CC} × 0.3		
Output voltage	V _{OH}	Min to Max	V _{CC} - 0.1	—	—	V	I _{OL} = -50 μA
		2.3	2.0	—	—		I _{OL} = -2 mA
		3.0	2.48	—	—		I _{OL} = -6 mA
		4.5	3.8	—	—		I _{OL} = -12 mA
	V _{OL}	Min to Max	—	—	0.1		I _{OL} = 50 μA
		2.3	—	—	0.4		I _{OL} = 2 mA
		3.0	—	—	0.44		I _{OL} = 6 mA
		4.5	—	—	0.55		I _{OL} = 12 mA
Input current	I _{IN}	0 to 5.5	—	—	±1	μA	V _{IN} = 5.5 V or GND
Quiescent supply current	I _{CC}	5.5	—	—	20	μA	V _{IN} = V _{CC} or GND, I _O = 0
Output leak current	I _{OFF}	0	—	—	5	μA	V _O = 5.5 V
Input capacitance	C _{IN}	3.3	—	1.6	—	pF	V _I = V _{CC} or GND

Note: For conditions shown as Min or Max, use the appropriate values under recommended operating conditions.

Switching Characteristics

$V_{CC} = 2.5 \pm 0.2 \text{ V}$

Item	Symbol	Ta = 25°C			Ta = -40 to 85°C		Unit	Test Conditions	FROM (Input)	TO (Output)
		Min	Typ	Max	Min	Max				
Propa- gation delay time	t_{PLH}	—	7.9	17.6	1.0	21.0	ns	$C_L = 15 \text{ pF}$	A or B	Y
	t_{PHL}	—	10.5	22.6	1.0	26.5		$C_L = 50 \text{ pF}$		

$V_{CC} = 3.3 \pm 0.3 \text{ V}$

Item	Symbol	Ta = 25°C			Ta = -40 to 85°C		Unit	Test Conditions	FROM (Input)	TO (Output)
		Min	Typ	Max	Min	Max				
Propa- gation delay time	t_{PLH}	—	7.0	11.0	1.0	13.0	ns	$C_L = 15 \text{ pF}$	A or B	Y
	t_{PHL}	—	9.5	14.5	1.0	16.5		$C_L = 50 \text{ pF}$		

$V_{CC} = 5.0 \pm 0.5 \text{ V}$

Item	Symbol	Ta = 25°C			Ta = -40 to 85°C		Unit	Test Conditions	FROM (Input)	TO (Output)
		Min	Typ	Max	Min	Max				
Propa- gation delay time	t_{PLH}	—	4.8	6.8	1.0	8.0	ns	$C_L = 15 \text{ pF}$	A or B	Y
	t_{PHL}	—	6.3	8.8	1.0	10.0		$C_L = 50 \text{ pF}$		

Operating Characteristics

$C_L = 50 \text{ pF}$

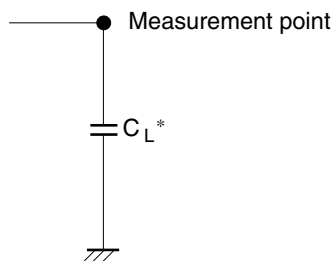
Item	Symbol	$V_{CC} \text{ (V)}$	$T_a = 25^\circ\text{C}$			Unit	Test Conditions
			Min	Typ	Max		
Power dissipation capacitance	C_{PD}	3.3	—	8.4	—	pF	$f = 10 \text{ MHz}$
		5.0	—	8.8	—		

Noise Characteristics

$C_L = 50 \text{ pF}$

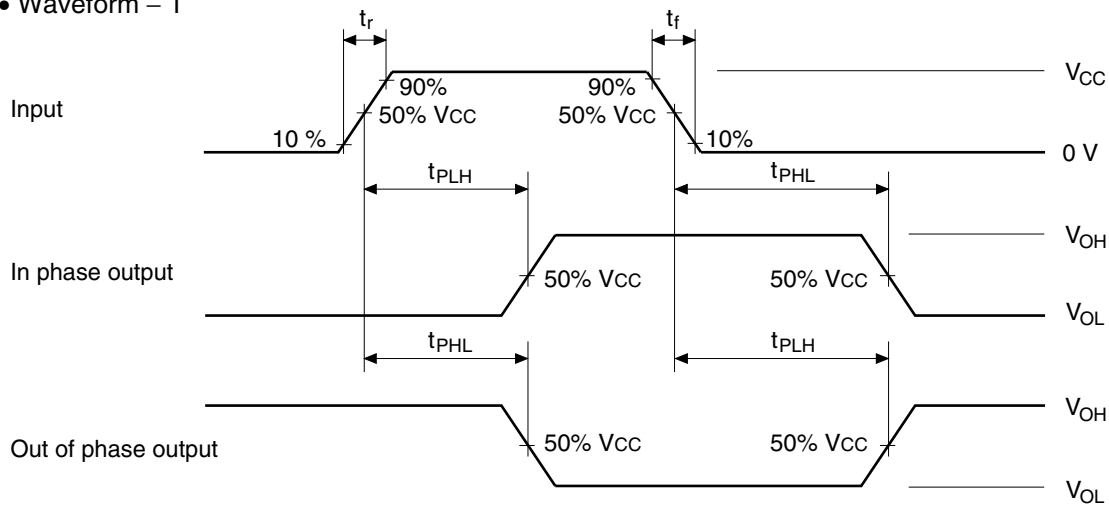
Item	Symbol	$V_{CC} \text{ (V)}$	$T_a = 25^\circ\text{C}$			Unit	Test Conditions
			Min	Typ	Max		
Quiet output, maximum dynamic V_{OL}	$V_{OL(P)}$	3.3	—	0.2	0.8	V	
Quiet output, minimum dynamic V_{OL}	$V_{OL(V)}$	3.3	—	−0.1	−0.8		
Quiet output, minimum dynamic V_{OH}	$V_{OH(V)}$	3.3	—	3.1	—		
High-level dynamic input voltage	$V_{IH(D)}$	3.3	2.31	—	—		
Low-level dynamic input voltage	$V_{IL(D)}$	3.3	—	—	0.99		

Test Circuit



Note: C_L includes the probe and jig capacitance.

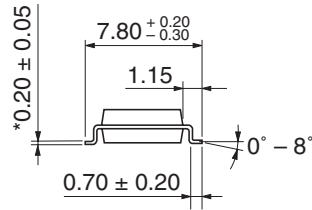
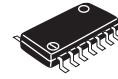
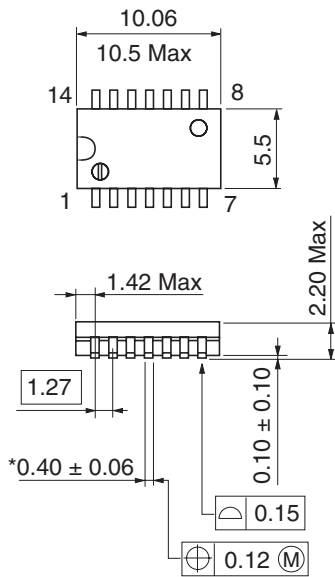
• Waveform – 1



- Notes: 1. Input waveform: $PRR \leq 1 \text{ MHz}$, $Z_o = 50 \Omega$, $t_r \leq 3 \text{ ns}$, $t_f \leq 3 \text{ ns}$
 2. The output are measured one at a time with one transition per measurement.

Package Dimensions

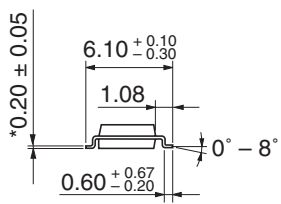
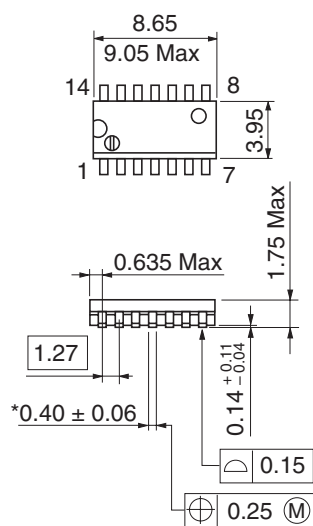
As of July, 2001
Unit: mm



*Pd plating

Hitachi Code	FP-14DAV
JEDEC	—
JEITA	Conforms
Mass (reference value)	0.23 g

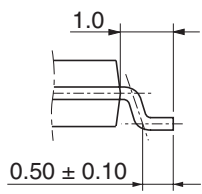
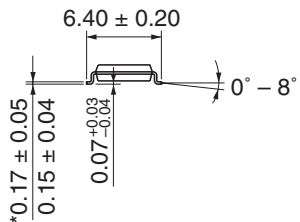
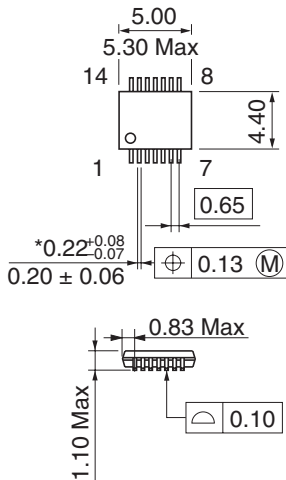
As of July, 2001
Unit: mm



Hitachi Code	FP-14DNV
JEDEC	Conforms
JEITA	Conforms
Mass (reference value)	0.13 g

*Pd plating

As of July, 2001
Unit: mm



Hitachi Code	TTP-14D
JEDEC	—
JEITA	—
Mass (reference value)	0.05 g

*Dimension including the plating thickness
Base material dimension

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